

3000W, 12V- 47V Surface Mount Transient Voltage Suppressor

FEATURES

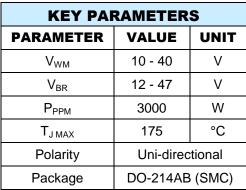
- AEC-Q101 qualified
- Moisture sensitivity level: level 1, per J-STD-020
- Meets IEC 61000-4-2 (Level: 4) / ISO 10605 (Level: L4)
- Meets ISO 7637-2 (Pulse 1/2a/2b/3a/3b)
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Motor for BLDC
- Lighting application
- Battery Management System
- Automotive

MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.210g (approximately)







DO-214AB (SMC)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	VALUE	UNIT		
Non-repetitive peak impulse power dissipation with 10/1000µs waveform ⁽¹⁾	P _{PPM}	3000	W		
Steady state power dissipation at $T_L = 25^{\circ}C^{(2)}$	P _D	8.5	W		
Peak forward surge current 8.3ms single half sine-wave	I _{FSM}	300	А		
Junction temperature	TJ	-55 to +175	°C		
Storage temperature	T _{STG}	-55 to +175	°C		

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Notes:

- 1. Non-repetitive current pulse per Fig.3 and derated above $T_A = 25^{\circ}$ C per Fig.1
- 2. Units mounted on PCB (16mm x 16mm Cu pad test board)

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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance	R _{OJL}	17	°C/W		
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	50	°C/W		
Junction-to-case thermal resistance	R _{eJC}	10	°C/W		

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)											
Part number Marking code		I _R max at V _{WM}		V _{BR} at I _T ⁽¹⁾			V _C at I _{PPM} 10 / 1000 μs		R _D 10 / 1000 μs	αT ⁽²⁾	
Part number	Marking code			Min	Тур	Max	I _T	Max			Max
		μA V		v		mA		V ⁽³⁾	A ⁽⁴⁾	Ω	10 ⁻⁴ /°C
3KSMC12AH	3K12A	5	10	11.4	12.0	12.6	1	17.0	176	0.028	7.8
3KSMC15AH	3K15A	3	13	14.3	15.0	15.8	1	21.5	140	0.046	8.4
3KSMC18AH	3K18A	3	15	16.7	17.6	18.5	1	24.4	123.0	0.055	8.8
3KSMC19AH	3K19A	3	16	17.8	18.7	19.6	1	26.0	115.4	0.063	8.8
3KSMC21AH	3K21A	3	18	20	21.1	22.2	1	29.2	102.7	0.079	9.2
3KSMC23AH	3K23A	3	20	22.2	23.4	24.6	1	32.4	92.6	0.097	9.4
3KSMC26AH	3K26A	3	22	24.4	25.7	27.0	1	35.5	84.5	0.116	9.6
3KSMC28AH	3K28A	3	24	26.7	28.1	29.5	1	38.9	77.1	0.140	9.6
3KSMC30AH	3K30A	3	26	28.9	30.4	31.9	1	42.1	71.3	0.164	9.7
3KSMC33AH	3K33A	3	28	31.1	32.7	34.3	1	45.4	66.1	0.192	9.8
3KSMC35AH	3K35A	3	30	33.3	35.1	36.9	1	48.4	62.0	0.215	9.9
3KSMC39AH	3K39A	3	33	36.7	38.6	40.5	1	53.3	56.3	0.261	10.0
3KSMC42AH	3K42A	3	36	40.0	42.1	44.2	1	58.1	48.4	0.331	10.0
3KSMC47AH	3K47A	3	40	44.4	46.7	49.0	1	64.5	43.5	0.409	10.1

Notes:

- 1. Pulse test: tp < 30ms
- 2. To calculate V_{BR} or V_{C} versus junction temperature, use following formulas:

 V_{BR} at $T_J = V_{BR}$ at 25°C x (1 + αT x (T_J -25))

 V_C at $T_J = V_C$ at 25°C x (1 + αT x (T_J -25))

3. To calculate maximum clamping voltage at other surge level, use the following formula:

 $V_{Cmax} = V_C - R_D x (I_{PP} - I_{PPappli})$ where $I_{PPappli}$ is the surge current in the application.

ORDERING INFORMATION				
ORDERING CODE	PACKAGE	PACKING		
3KSMCxAH	DO-214AB (SMC)	3,000 / Tape & Reel		

Notes:

1. "x" defines voltage from 12V (3KSMC12AH) to 47V (3KSMC47AH)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Pulse Power or Current vs. Initial Junction Temperature

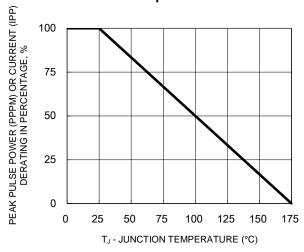


Fig.3 Clamping Power Pulse Waveform

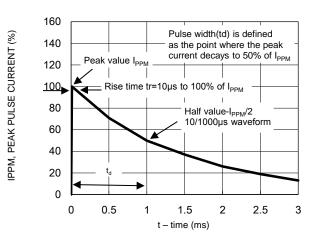


Fig.5 Typical Transient Thermal Impedance

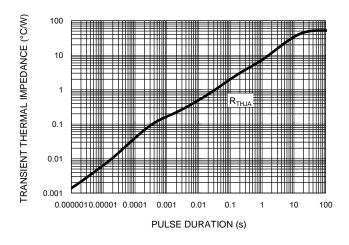


Fig.2 Steady State Power Derating

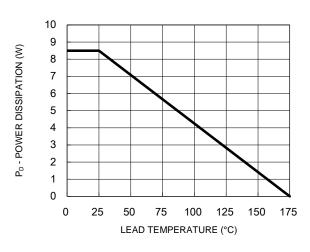


Fig.4 Typical Junction Capacitance

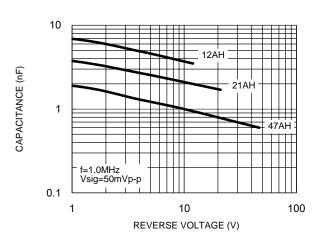
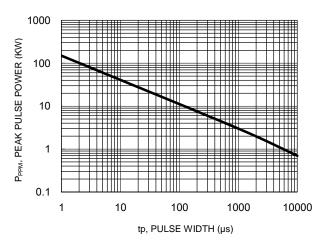


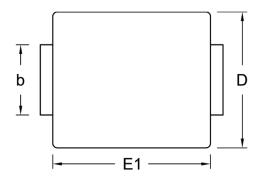
Fig.6 Peak Pulse Power Rating Cure

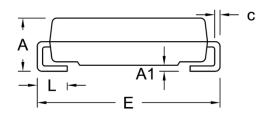




PACKAGE OUTLINE DIMENSIONS

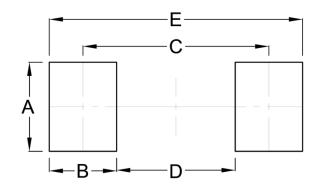
DO-214AB (SMC)





DIM.	Unit (mm)		Unit ((inch)	
DIIVI.	Min.	Min. Max.		Max.	
Α	2.00	2.62	0.079	0.103	
A1	-	0.20	-	0.008	
b	2.90	3.20	0.114	0.126	
С	0.15	0.31	0.006	0.012	
D	5.59	6.22	0.220	0.245	
E	7.75	8.13	0.305	0.320	
E1	6.60	7.11	0.260	0.280	
L	1.00	1.60	0.039	0.063	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

MARKING DIAGRAM



P/N = Marking Code G = Green Compound

ΥW = Date Code F = Factory Code



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